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1753

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/831,763

Filed: May 11, 2001

Inventor(s): Heinrich Meyer et al.

For: "Method of Galvanically Forming
Conductor Structures of High-Purity
Copper in-the Production of Integrated
Circuits"

Examiner: Mutschler, Brian L.

Art Unit: 1753

Attorney Docket No.: 071-01

<p>CERTIFICATE OF MAILING DATE OF DEPOSIT: May 10, 2004 I hereby certify that this correspondence is being deposited with the United States Postal Service, postage paid, as first class mail under 37 C.F.R. §1.8, on the date indicated above and is addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.</p> <p>Name of person mailing paper or fee: Ourmazd S. Ojan</p> <p>Signature: <u><i>Ourmazd S. Ojan</i></u></p>
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Mail Stop *AF*
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

COVER LETTER AND CERTIFICATE OF MAILING

Sir:

Enclosed and attached hereto are the following:

- 1) This cover letter with Certificate of Mailing (in duplicate);
- 2) Petition for one-month extension of time (1 page; in duplicate);
- 3) Amendment (13 pages);
- 4) Exhibits A through E;
- 5) Check in the amount of \$110.00 for the extension fee; and
- 6) Postcard to be date stamped and returned by PTO.

No additional fees are believed to be required at this time. In the event that additional fees are required with respect to this communication, the Commissioner is hereby authorized to charge any such fees, or credit any overpayment, to Paul & Paul deposit account number 16-0750.

May 10, 2004

Respectfully submitted,

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